

/ Descriptions

Silicon NPN transistor in a TO-18 Plastic Package.

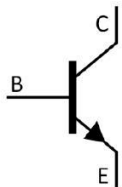
/ Features

Low $V_{CE(sat)}$, excellent DC current gain, complements the 2SB1436.

/ Applications

Strobe flash applications, general power amplifier applications.

/ Equivalent Circuit



/ Pinning



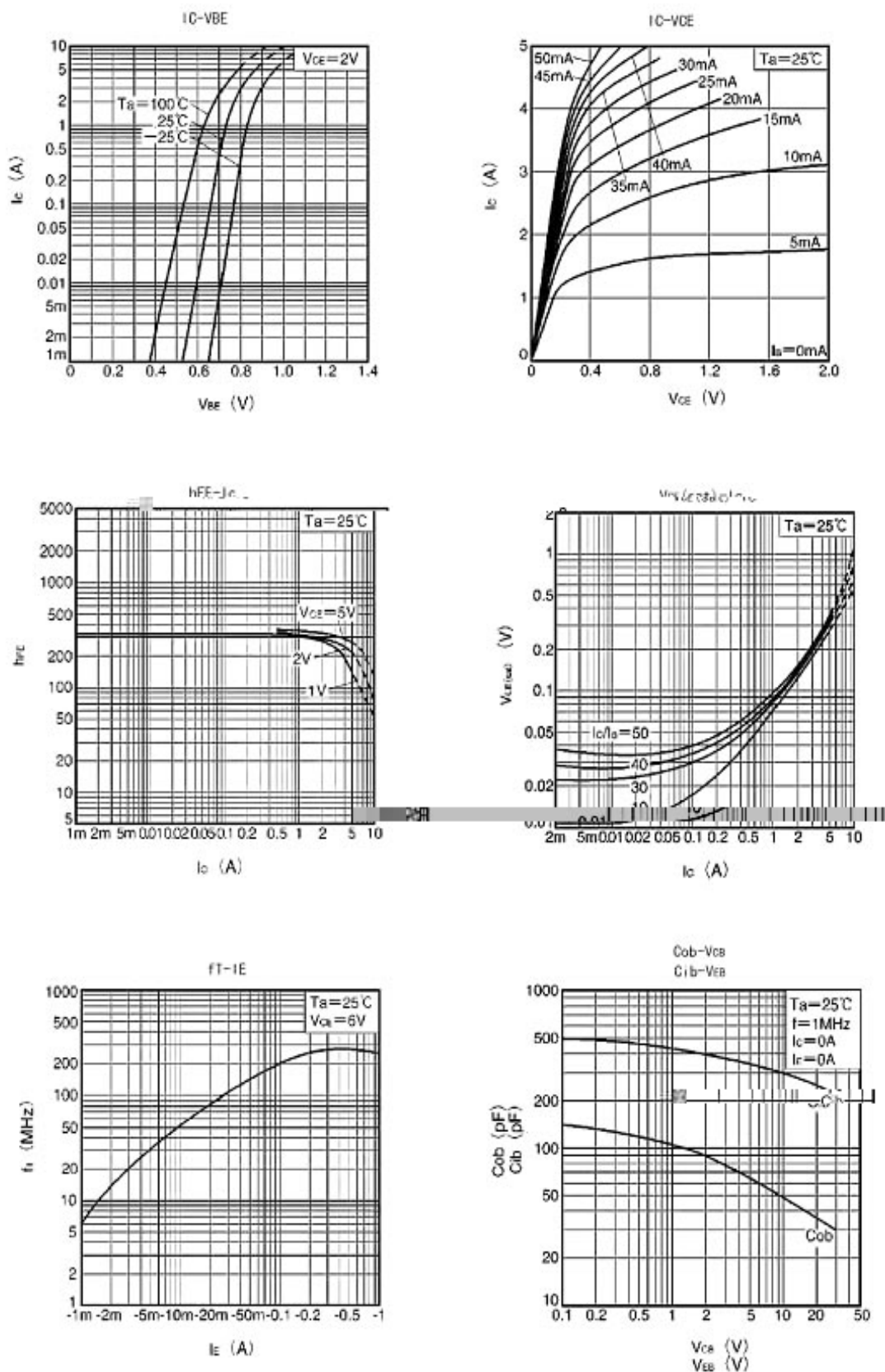
PIN1 Emitter PIN 2 Collector PIN 3 Base

/ h_{FE} Classifications & Marking

h_{FE} Classifications Symbol	Q	R
h_{FE} Range	120 270	180 390

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	50	V
Collector to Emitter Voltage	V_{CEO}	20	V
Emitter to Base Voltage	V_{EBO}	6.0	V
Collector Current - Continuous	I_C	5.0	A
Collector Current – Continuous(Pulse)	I_{CP}	10	A
Collector Power Dissipation	P_C	1.5	W
Collector Power Dissipation	$P_C(T_c=25^\circ C)$	5.0	W
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	Applicable to the entire storage temperature range	

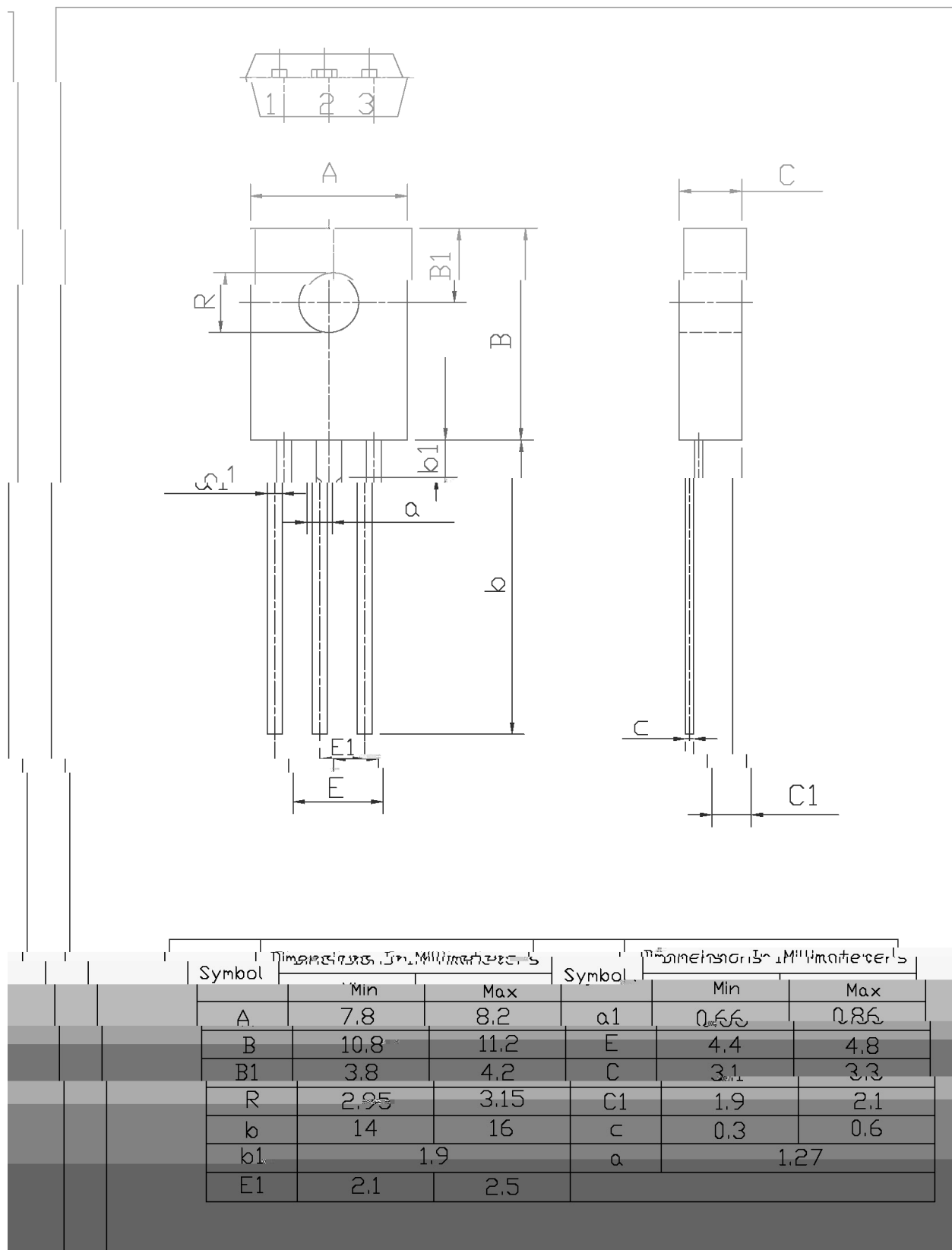
/ Electrical Characteristic Curve



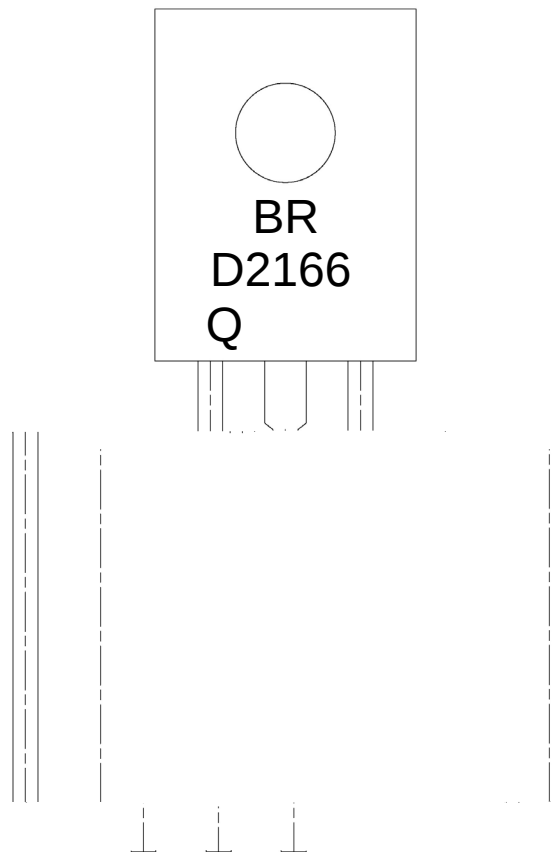
/ Package Dimensions

2SD2166

单位: mm



/ Marking Instructions



Note:

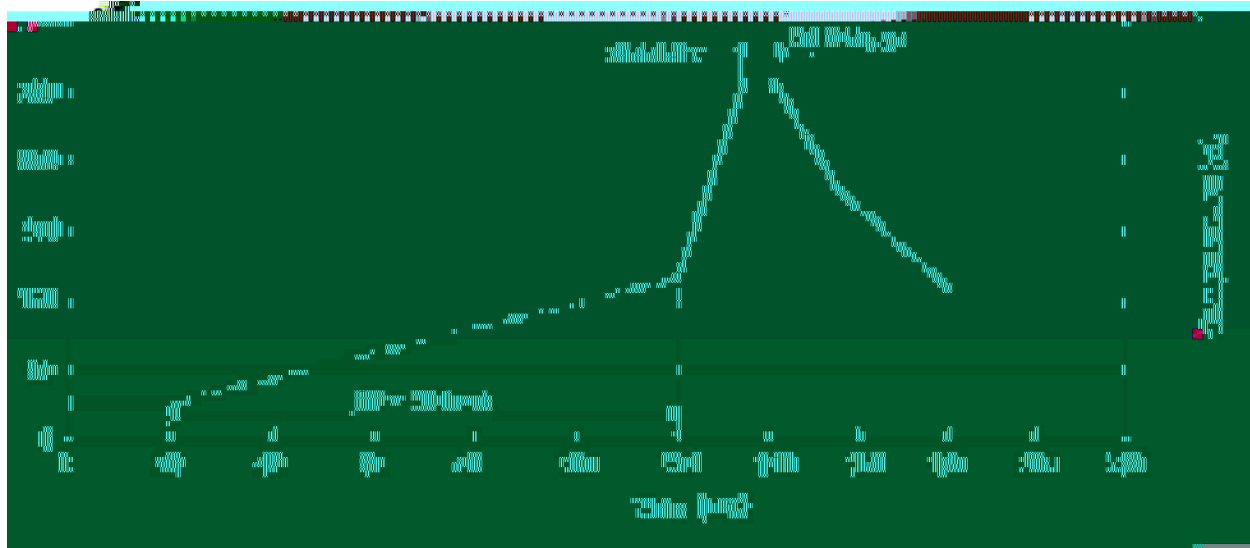
BR: Company Code

D2166: Product Type.

Q: h_{FE} Classifications Symbol

***: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-----|-----|----|---------|---|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255 | 5 | 5 | 0.5sec; | 2.Peak Temp.:255 5 , Duration:5 0.5sec. |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

270 5 10 1 sec. Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只 套管	套管 盒	只 盒	盒 箱	只 箱	套管	盒	箱

/ TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只 套管	套管 盒	只 盒	盒 箱	只 箱	套管	盒	箱

/ Notices